

- Tentative Specification
- Preliminary Specification
- Approval Specification

MODEL NO.: M170EGE
SUFFIX: L20

Customer: ALL	
APPROVED BY	SIGNATURE
Name / Title _____	_____
Note	
<p>_____</p> <p>Please return 1 copy for your confirmation with your signature and comments.</p>	

Approved By	Checked By	Prepared By
阮泰郎	林秋森	阮志昌

CONTENTS

1. GENERAL DESCRIPTION	5
1.1 OVERVIEW	5
1.2 GENERAL SPECIFICATIONS	5
2. MECHANICAL SPECIFICATIONS	5
3. ABSOLUTE MAXIMUM RATINGS	6
3.1 ABSOLUTE RATINGS OF ENVIRONMENT	6
3.2 ELECTRICAL ABSOLUTE RATINGS	6
3.2.1 TFT LCD MODULE	6
3.2.2 BACKLIGHT UNIT	7
4. ELECTRICAL SPECIFICATIONS	7
4.1 FUNCTION BLOCK DIAGRAM	7
4.2. INTERFACE CONNECTIONS	8
4.3 ELECTRICAL CHARACTERISTICS	9
4.3.1 LCD ELETRONICS SPECIFICATION	9
4.3.2 VCC POWER DIP CONDITION	12
4.3.3 BACKLIGHT UNIT	12
4.3.4 LIGHTBAR CONNECTOR PIN ASSIGNMENT	13
4.4 LVDS INPUT SIGNAL SPECIFICATIONS	14
4.4.1 LVDS DATA MAPPING TABLE	14
4.4.2 COLOR DATA INPUT ASSIGNMENT	15
4.5 DISPLAY TIMING SPECIFICATIONS	16
4.6 POWER ON/OFF SEQUENCE	18
5. OPTICAL CHARACTERISTICS	19
5.1 TEST CONDITIONS	19
5.2 OPTICAL SPECIFICATIONS	19
6. RELIABILITY TEST ITEM	22
7. MECHANICAL STRENGTH CHARACTERISTICS	23
7.1 MECHANICAL STRENGTH SPECIFICATIONS	23
7.2 TEST CONDITIONS	23
7.3 DEFINITION OF TEST POINTS	23
8. PACKING	24
8.1 PACKING SPECIFICATIONS	24
8.2 PACKING METHOD	24
8.3 PALLET	24
9. INX MODULE LABEL	25
10. PRECAUTIONS	26
10.1 ASSEMBLY AND HANDLING PRECAUTIONS	26
10.2 STORAGE PRECAUTIONS	26
10.3 OPERATION PRECAUTIONS	26
10.4 SAFETY PRECAUTIONS	26
10.5 SAFETY STANDARDS	26
10.6 OTHER	26
APPENDIX 1. SYSTEM COVER DESIGN NOTICE	27
APPENDIX 2. OUTLINE DRAWING	30

REVISION HISTORY

Version	Date	Page	Description
1.0	2011-10-17	All	Spec Ver.1.0 was first issued.
1.1	2011-11-23	Page 23	Cushion changed, packing method changed.
1.1	2011-11-23	Page 25	Unified CMI label.
1.2	2012-1-10	Page 12	Add Note(4).
1.3	2012-2-20	Page 13	Add connector type description.
1.4	2012-3-19	Page 5	Cell Power Consumption was changed.
1.4	2012-3-19	Page 9	Power Supply Current and Power Consumption were changed.
1.4	2012-3-19	Page 16	LVDS Clock (Spread spectrum modulation frequency) Max waschanged.
1.4	2012-3-19	Page 18	T1 and T7 were changed.
1.5	2012-5-2	Page 8	Note (1) was changed.
1.5	2012-5-2	Page 12	LED Life Time was changed.
1.5	2012-5-2	Page 13	(1) was changed.
1.5	2012-5-2	Page 14	Note (1) was changed.
1.5	2012-5-2	Page 23	Altitude test/operation was changed.
2.0	2017-4-10	All	Spec Ver.2.0 was first issued for ES7.0.
2.0	2017-4-10	5	1.2 power consumption : Total 8.95W(max)@cell 2.90W(max), BL6.05W(max)
2.0	2017-4-10	6	3.1 ABSOLUTE RATINGS OF ENVIRONMENT: Note (2) panel surface temp 65degC(max)
2.0	2017-4-10	7	3.2.2 BACKLIGHT UNIT: LED forward current per input pin typ 40mA, max 44mA
2.0	2017-4-10	9	4.3.1 LCD ELETRONICS SPECIFICATION: LVDS common input voltage min 1.0V, typ1.2V, max 1.4V
2.0	2017-4-10	12	4.3.3 BACKLIGHT UNIT: Backlight unit electrical specification table

Version	Date	Page	Description
2.0	2017-4-10	13	4.3.4 LIGHTBAR Connector Pin Assignment LIGHTBAR Connector updated. Pin Assignment (1)Connector(wire type): FCN(WM13-406-063N)or CviLux (CI1406M1HRK-NH). (2)L/B connector drawing. WM13-406-063N (FCN)
2.0	2017-4-10	14	CN1 Note(1) Note (1) User's Mating Connector Part No: FCN(WF1300106-B) or CviLux (CI1406SL000-NH)
2.0	2017-4-10	16	4.5 DISPLAY TIMING SPECIFICATIONS Note (2), (3) added.
2.0	2017-4-10	19	5.1 TEST CONDITIONS Test conditions updated.
2.0	2017-4-10	22	7. Mechanical Strength Characteristics added.
2.0	2017-4-10	24	8.1 PACKING SPECIFICATIONS updated
2.0	2017-4-10	24	8.3 Pallet specification updated.
2.0	2017-4-10	25	9. INX Module Label updated.
2.0	2017-4-10	26	(e) FAB ID (UL Factory ID) updated. "VIRO " is added.
2.0	2017-4-10	26~30	Appendix 1 ~ 5 added.

1. GENERAL DESCRIPTION

1.1 OVERVIEW

M170EGE-L20 is a 17" TFT Liquid Crystal Display module with WLED Backlight unit and 30 pins 2ch-LVDS interface. This module supports 1280 x 1024 SXGA mode and can display up to 16.7M colors. The converter module for Backlight is not built in.

1.2 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Screen Size	17" real diagonal	-	-
Driver Element	a-si TFT active matrix	-	-
Pixel Number	1280 x R.G.B. x 1024, SXGA resolution	pixel	-
Pixel Pitch	0.264 (H) x 0.264 (V)	mm	-
Pixel Arrangement	RGB vertical stripe	-	-
Display Colors	16.7M	color	-
Transmissive Mode	Normally white	-	-
Surface Treatment	AG type, 3H hard coating, Haze 25	-	-
Luminance, White	250nits (Typ.)	Cd/m2	
Color Gamut	72% of NTSC(Typ.)	-	-
ROHS, Halogen Free & TCO 5.2	ROHS, Halogen Free, TCO 5.2 compliance		
Power Consumption	Total 8.95W (Max.) @ cell 2.90 W (Max.), BL6.05W (Max.)		(1)

Note (1) The specified power consumption : Total= cell (reference 4.3.1)+BL (reference 4.3.3)

2. MECHANICAL SPECIFICATIONS

Item	Min.	Typ.	Max.	Unit	Note	
Module Size	Horizontal (H)	358.0	358.5	359.0	mm	(1)
	Vertical (V)	296.0	296.5	297.0	mm	
	Thickness (T)	-	10.5	11.0	mm	
Bezel Area	Horizontal	341.7	341.9	342.1	mm	
	Vertical	274.2	274.4	274.6	mm	
Active Area	Horizontal	-	337.92	-	mm	
	Vertical	-	270.336	-	mm	
Weight	-	1400	1500	g		

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

3. ABSOLUTE MAXIMUM RATINGS

3.1 ABSOLUTE RATINGS OF ENVIRONMENT

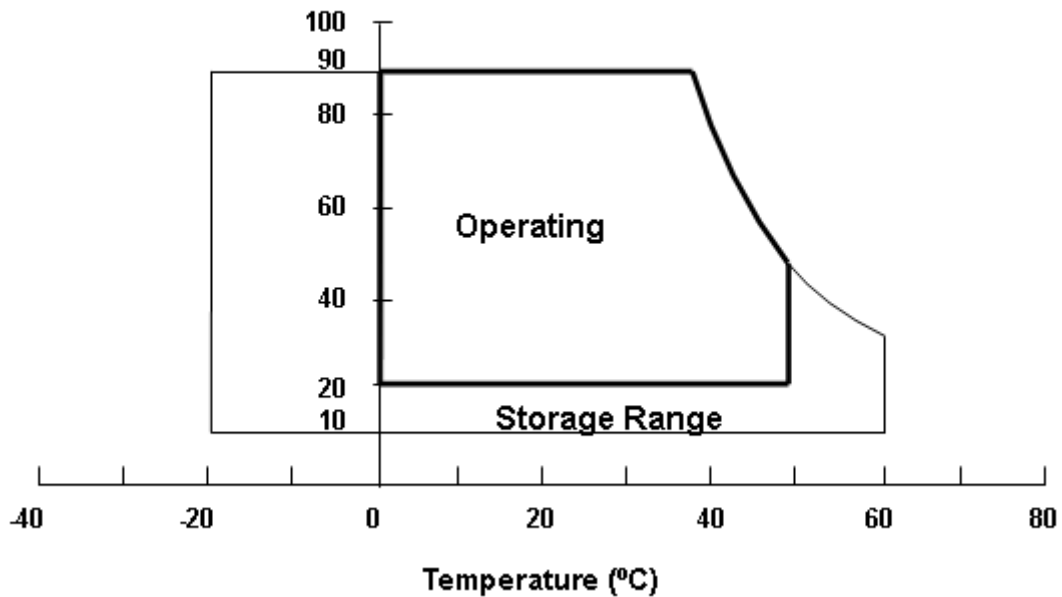
Item	Symbol	Value		Unit	Note
		Min.	Max.		
Storage Temperature	TST	-20	60	°C	(1)
Operating Ambient Temperature	TOP	0	50	°C	(1), (2)

Note (1)

- (a) 90 %RH Max. ($T_a \leq 40\text{ °C}$).
- (b) Wet-bulb temperature should be 39 °C Max. ($T_a > 40\text{ °C}$).
- (c) No condensation.

Note (2) Panel surface temperature should be 0°C min. and 65°C max under $V_{CC}=5.0V$, $f_r=60Hz$, typical LED string current, 25°C ambient temperature, and no humidity control. Any condition of ambient operating temperature, the surface of active area should be keeping not higher than 65°C.

Relative Humidity (%RH)



3.2 ELECTRICAL ABSOLUTE RATINGS

3.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Power Supply Voltage	VCCS	-0.3	6.0	V	(1)
Logic Input Voltage	V_{IN}	-0.3	3.6	V	

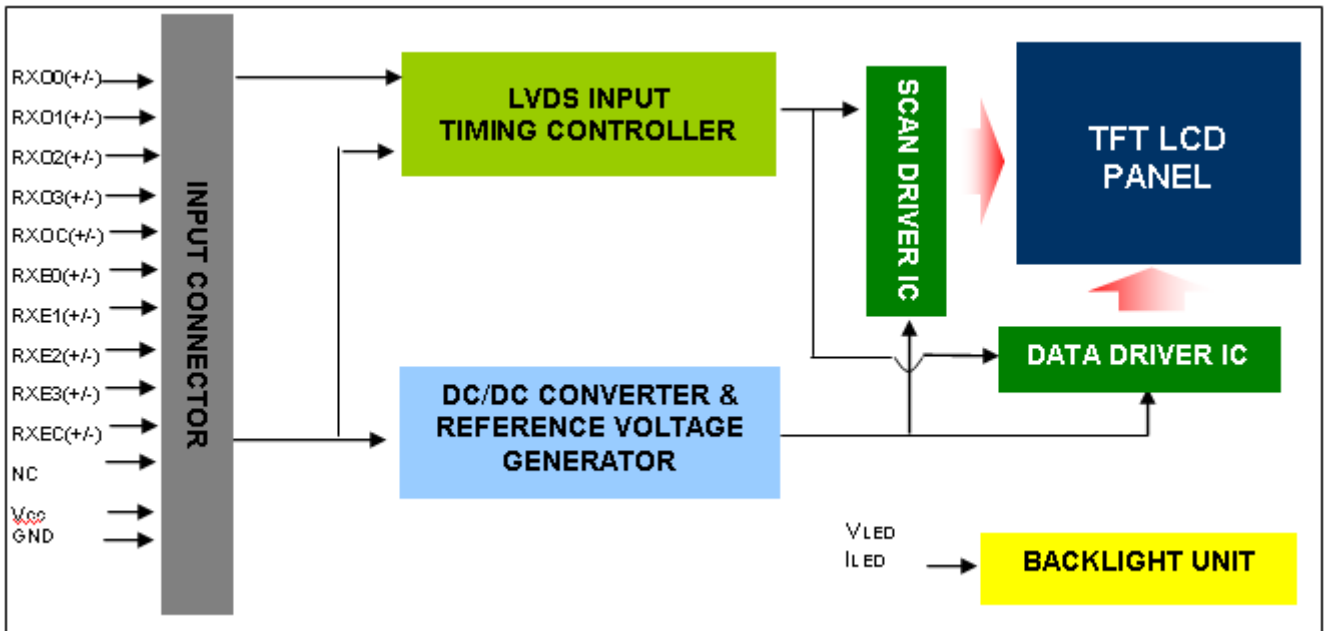
3.2.2 BACKLIGHT UNIT

Item	Symbol	Value			Unit	Note
		Min.	Typ	Max.		
LED Forward Current Per Input Pin	I_F	0	40	44	mA	(1), (2) Duty=100%
LED Pulse Forward Current Per Input Pin	I_P	---	---	150	mA	(1), (2) Pulse Width \leq 10msec. and Duty \leq 30%

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.
 Note (2) Specified values are for input pin of LED light bar at $T_a=25\pm 2\text{ }^\circ\text{C}$ (Refer to 4.3.3 and 4.3.4 for further information).

4. ELECTRICAL SPECIFICATIONS

4.1 FUNCTION BLOCK DIAGRAM



4.2. INTERFACE CONNECTIONS

PIN ASSIGNMENT

Pin	Name	Description
1	RXO0-	Negative LVDS differential data input. Channel O0 (odd)
2	RXO0+	Positive LVDS differential data input. Channel O0 (odd)
3	RXO1-	Negative LVDS differential data input. Channel O1 (odd)
4	RXO1+	Positive LVDS differential data input. Channel O1 (odd)
5	RXO2-	Negative LVDS differential data input. Channel O2 (odd)
6	RXO2+	Positive LVDS differential data input. Channel O2 (odd)
7	GND	GND
8	RXOC-	Negative LVDS differential clock input. (odd)
9	RXOC+	Positive LVDS differential clock input. (odd)
10	RXO3-	Negative LVDS differential data input. Channel O3(odd)
11	RXO3+	Positive LVDS differential data input. Channel O3 (odd)
12	RXE0-	Negative LVDS differential data input. Channel E0 (even)
13	RXE0+	Positive LVDS differential data input. Channel E0 (even)
14	GND	GND
15	RXE1-	Negative LVDS differential data input. Channel E1 (even)
16	RXE1+	Positive LVDS differential data input. Channel E1 (even)
17	GND	GND
18	RXE2-	Negative LVDS differential data input. Channel E2 (even)
19	RXE2+	Positive LVDS differential data input. Channel E2 (even)
20	RXEC-	Negative LVDS differential clock input. (even)
21	RXEC+	Positive LVDS differential clock input. (even)
22	RXE3-	Negative LVDS differential data input. Channel E3(even)
23	RXE3+	Positive LVDS differential data input. Channel E3 (even)
24	GND	GND
25	NC	For LCD internal use only, Do not connect
26	NC	For LCD internal use only, Do not connect
27	NC	For LCD internal use only, Do not connect
28	Vcc	+5.0V power supply
29	Vcc	+5.0V power supply
30	Vcc	+5.0V power supply

Note (1) Connector Part No.: Foxconn:GS23301-0321R-7H or P-TWO:187098-30091 or FCN:WF13-422-3033

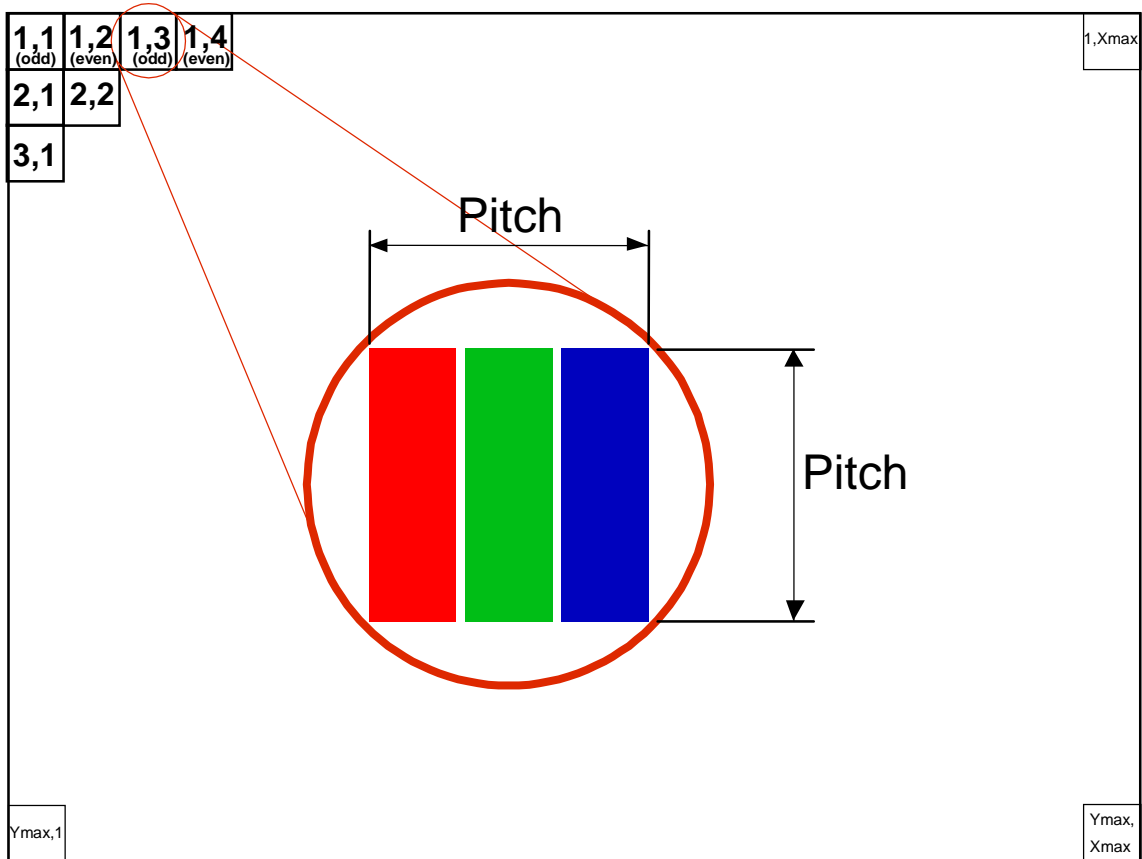
Note (2) User's connector Part No:

Mating Wire Cable Connector Part No.: FI-X30H(JAE) or FI-X30HL(JAE)

Mating FFC Cable Connector Part No.: 217007-013001 (P-TWO) or JF05X030-1 (JAE).

Note (3) The first pixel is odd.

Note (4) Input signal of even and odd clock should be the same timing.



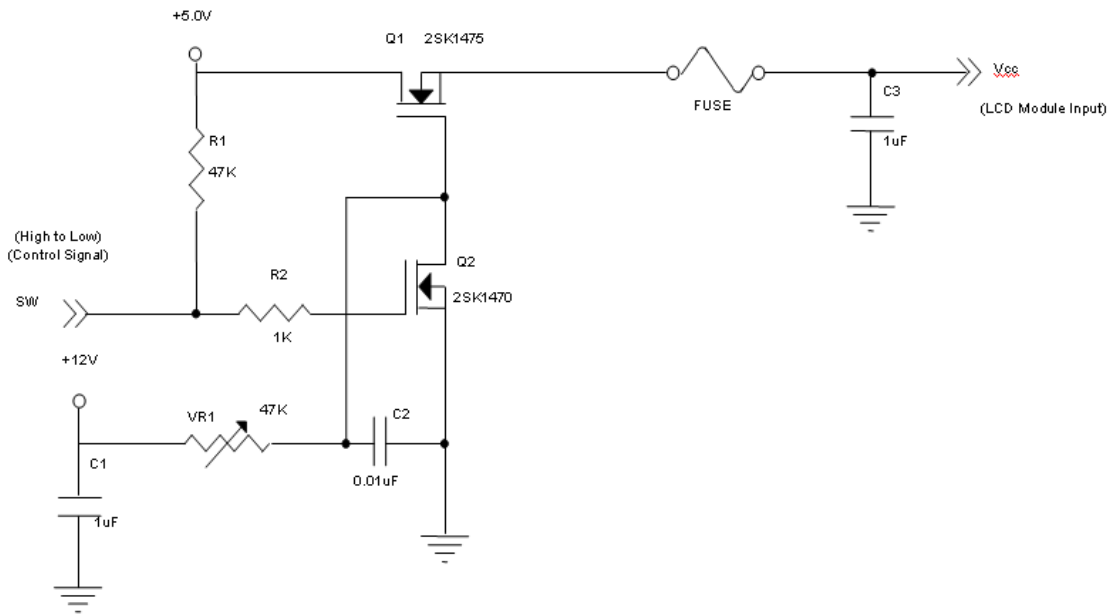
4.3 ELECTRICAL CHARACTERISTICS

4.3.1 LCD ELETRONICS SPECIFICATION

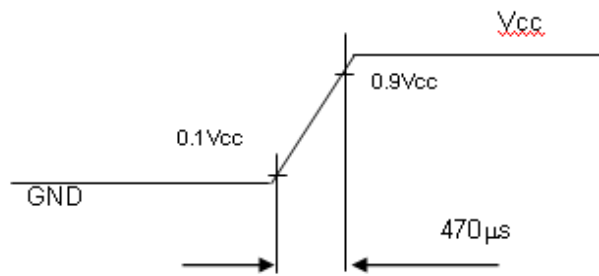
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
Power Supply Voltage	V _{CC}	4.5	5	5.5	V	-
Ripple Voltage	V _{RP}			300	mV	-
Rush Current	I _{RUSH}			2	A	(2)
Power Supply Current	White		335	390	mA	(3)a
	Black		490	580	mA	(3)b
	Vertical Stripe		420	490	mA	(3)c
Power Consumption	PLCD		2.45	2.90	Watt	(4)
LVDS differential input voltage	V _{id}	100		600	mV	(5)
LVDS common input voltage	V _{ic}	1.0	1.2	1.4	V	(5)
Logic High Input Voltage	V _{IH}			100	mV	(5)
Logic Low Input Voltage	V _{IL}	-100			mV	(5)

Note (1) The ambient temperature is $T_a = 25 \pm 2$ °C.

Note (2) Measurement Conditions:21



Vcc rising time is 470μs



Note (3) The specified power supply current is under the conditions at $V_{CC} = 5.0\text{ V}$, $T_a = 25 \pm 2\text{ }^\circ\text{C}$, $F_r = 75\text{ Hz}$, whereas a power dissipation check pattern below is displayed.

a. White Pattern



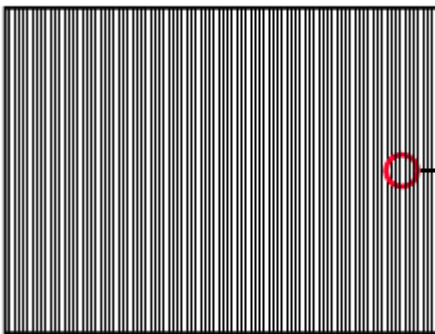
Active Area

b. Black Pattern

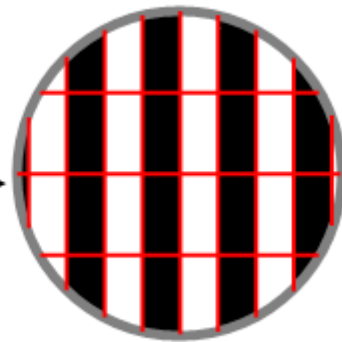


Active Area

c. Vertical Stripe Pattern

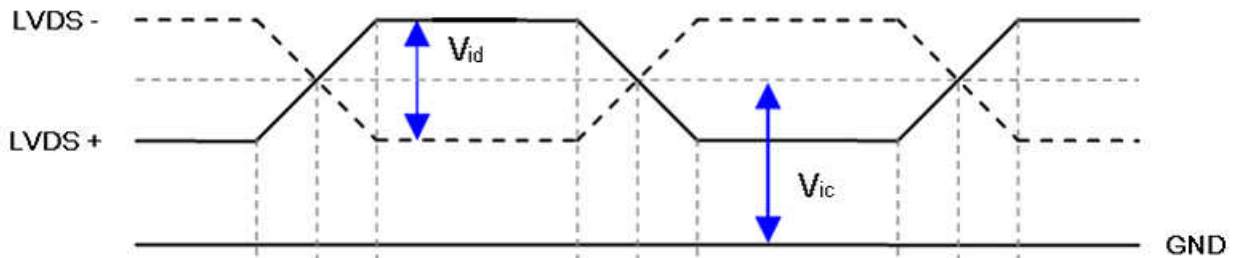


Active Area

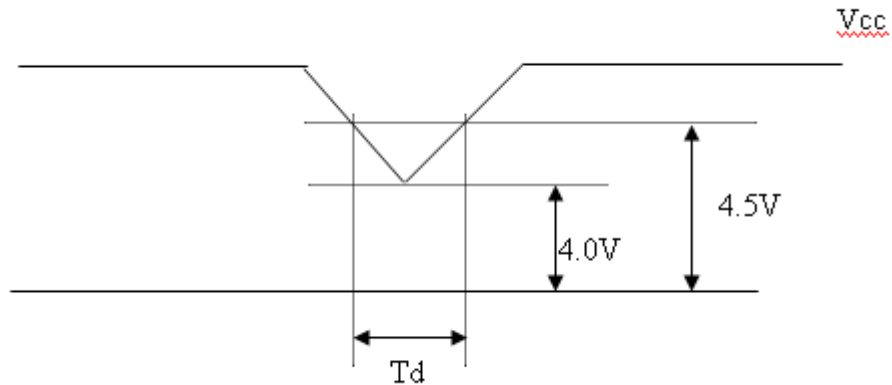


Note (4) The power consumption is specified at the pattern with the maximum current.

Note (5) VID waveform condition



4.3.2 VCC POWER DIP CONDITION



Dip condition: $4.0 \leq V_{cc} \leq 4.5$, $T_d \leq 20\text{ms}$

4.3.3 BACKLIGHT UNIT

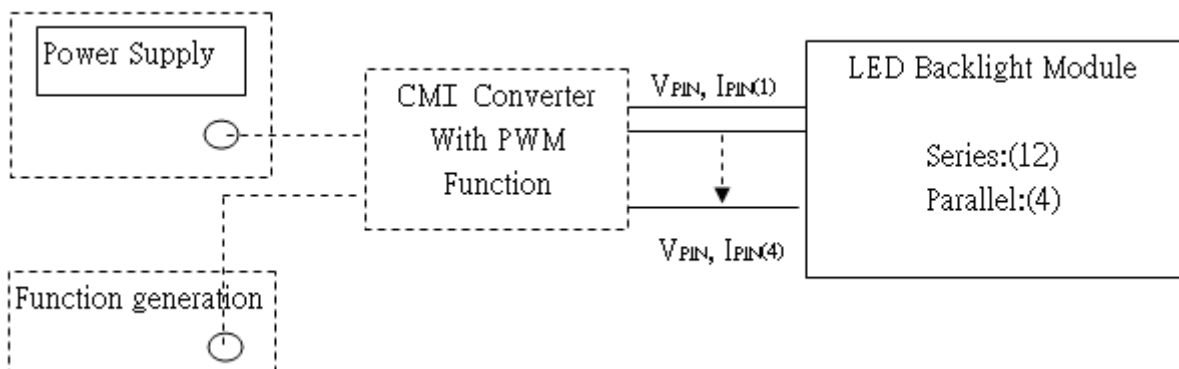
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
LED Light Bar Input Voltage Per Input Pin	VPIN	34.2	36	37.8	V	(1), Duty=100%,
LED Light Bar Current Per Input Pin	IPIN	37.6	40	42.4	mA	(1), (2) Duty=100%
LED Life Time	LLED	50000			Hrs	(3)
LED Light Bar Power Consumption	PBL	---	5.76	6.05	W	(1) Duty=100%,

Note (1) LED light bar input voltage and current are measured by utilizing a true RMS multimeter as shown below:

Note (2) $PBL = IPIN \times VPIN \times (4)$ PBL.

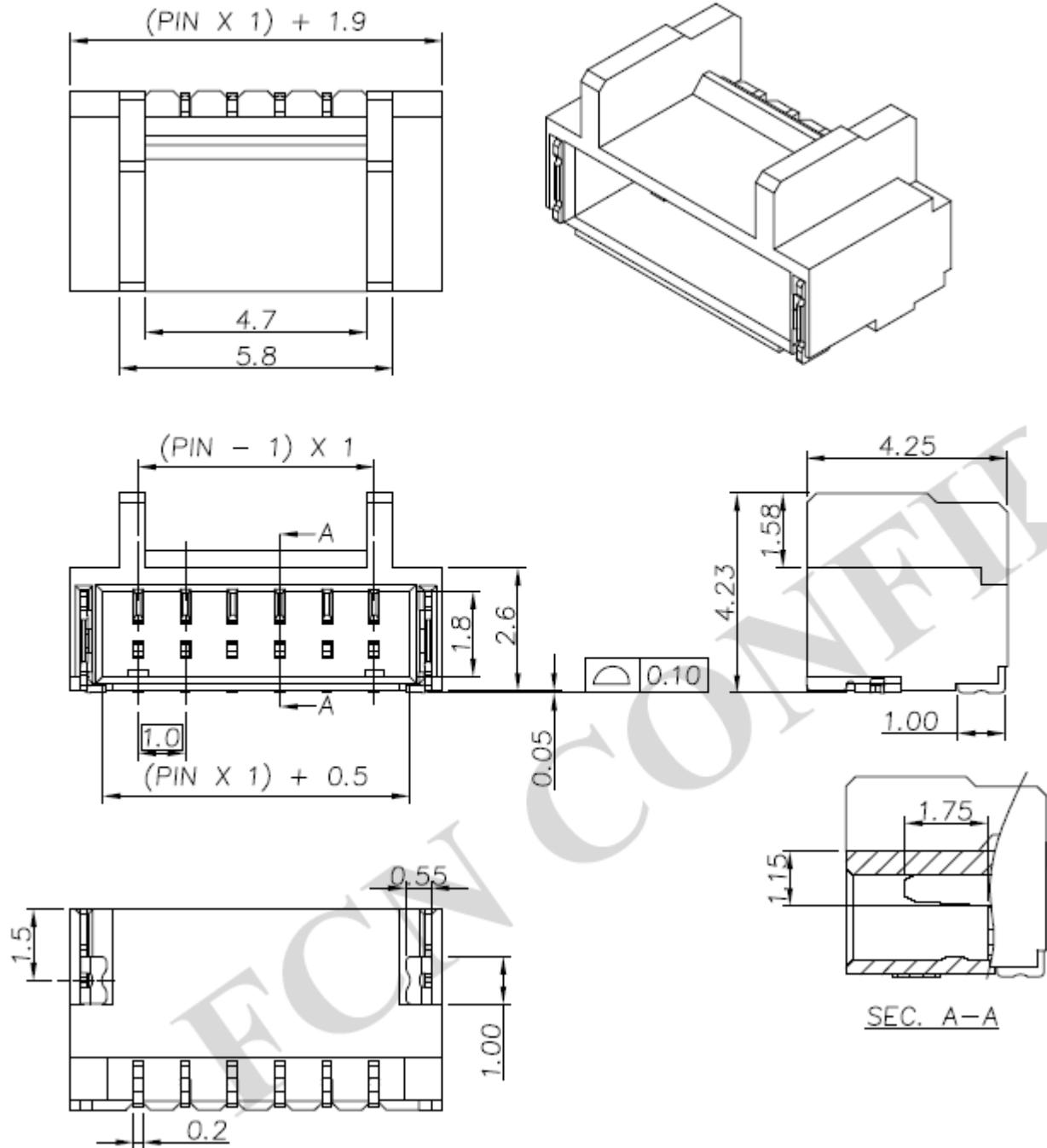
Note (3) The lifetime of LED is defined as the time when LED packages continue to operate under the conditions at $T_a = 25 \pm 2 \text{ }^\circ\text{C}$ and $I = (65)\text{mA}$ (per chip) until the brightness becomes $\leq 50\%$ of its original value.

Note (4) The module must be operated with constant driving current.



4.3.4 LIGHTBAR CONNECTOR PIN ASSIGNMENT

- (1) Connector(wire type): FCN(WM13-406-063N) or CviLux(CI1406M1HRK-NH).
- (2) L/B connector drawing. WM13-406-063N (FCN)

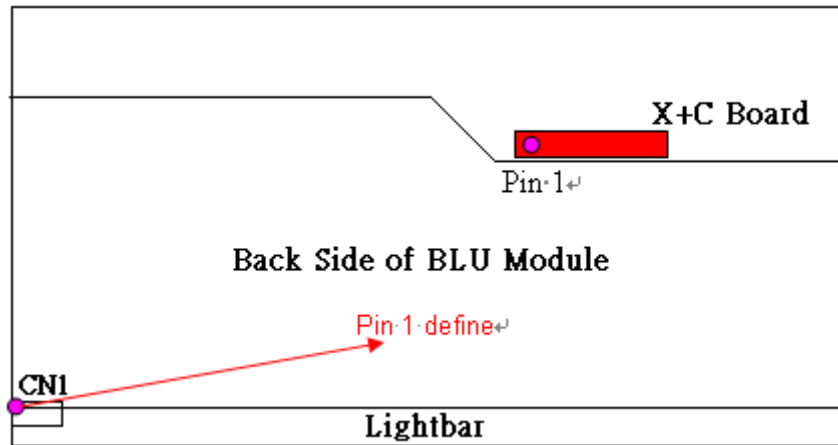


Other equivalents please refer to individual drawing

CN1

Pin number	Description
1	Cathode of LED string
2	Cathode of LED string
3	VLED
4	VLED
5	Cathode of LED string
6	Cathode of LED string

Note (1) User's Mating Connector Part No.:FCN(WF1300106-B) or CviLux(C11406SL000-NH)and hook width must be less than 4.5mm.



4.4 LVDS INPUT SIGNAL SPECIFICATIONS

4.4.1 LVDS DATA MAPPING TABLE

LVDS Channel O0	LVDS output	D7	D6	D4	D3	D2	D1	D0
	Data order	OG0	OR5	OR4	OR3	OR2	OR1	OR0
LVDS Channel O1	LVDS output	D18	D15	D14	D13	D12	D9	D8
	Data order	OB1	OB0	OG5	OG4	OG3	OG2	OG1
LVDS Channel O2	LVDS output	D26	D25	D24	D22	D21	D20	D19
	Data order	DE	NA	NA	OB5	OB4	OB3	OB2
LVDS Channel O3	LVDS output	D23	D17	D16	D11	D10	D5	D27
	Data order	NA	OB7	OB6	OG7	OG6	OR7	OR6
LVDS Channel E0	LVDS output	D7	D6	D4	D3	D2	D1	D0
	Data order	EG0	ER5	ER4	ER3	ER2	ER1	ER0
LVDS Channel E1	LVDS output	D18	D15	D14	D13	D12	D9	D8
	Data order	EB1	EB0	EG5	EG4	EG3	EG2	EG1
LVDS Channel E2	LVDS output	D26	D25	D24	D22	D21	D20	D19
	Data order	DE	NA	NA	EB5	EB4	EB3	EB2
LVDS Channel E3	LVDS output	D23	D17	D16	D11	D10	D5	D27
	Data order	NA	EB7	EB6	EG7	EG6	ER7	ER6

4.4.2 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input, the brighter the color. The table below provides the assignment of color versus data input.

Color		Data Signal																						
		Red								Green								Blue						
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1
Basic Colors	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Gray Scale Of Red	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
Gray Scale Of Green	Green(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	
	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	Green(253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	
	Green(254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	
	Green(255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	
Gray Scale Of Blue	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	
	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	
	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	
	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	

Note (1) 0: Low Level Voltage, 1: High Level Voltage

4.5 DISPLAY TIMING SPECIFICATIONS

The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
LVDS Clock	Frequency	Fc	45	54	69.3	MHz	-
	Period	Tc	14.43	18.52	22.22	ns	
	Input cycle to cycle jitter	T _{rdl}	-0.02*TC	---	0.02*TC	ns	(4)
	Input Clock to data skew	TLVCCS	-0.02*TC	---	0.02*TC	ns	(5)
	Spread spectrum modulation range	F _{clkin_mod}	0.97*FC	---	1.03*FC	MHz	(6)
	Spread spectrum modulation frequency	F _{SSM}			100	KHz	
Vertical Display Term	Frame Rate	Fr	50	60	75	Hz	
	Total	Tv	1044	1066	1450	Th	Tv=Tvd+Tvb-
	Active Display	Tvd		1024		Th	-
	Blank	Tvb	20	42		Th	-
Horizontal Display Term	Total	Th	790	844	880	Tc	Th=Thd+Thb
	Active Display	Thd		640		Tc	-
	Blank	Thb	150	204		Tc	-

Note: (1) Because this module is operated by DE only mode, Hsync and Vsync input signals are ignored.

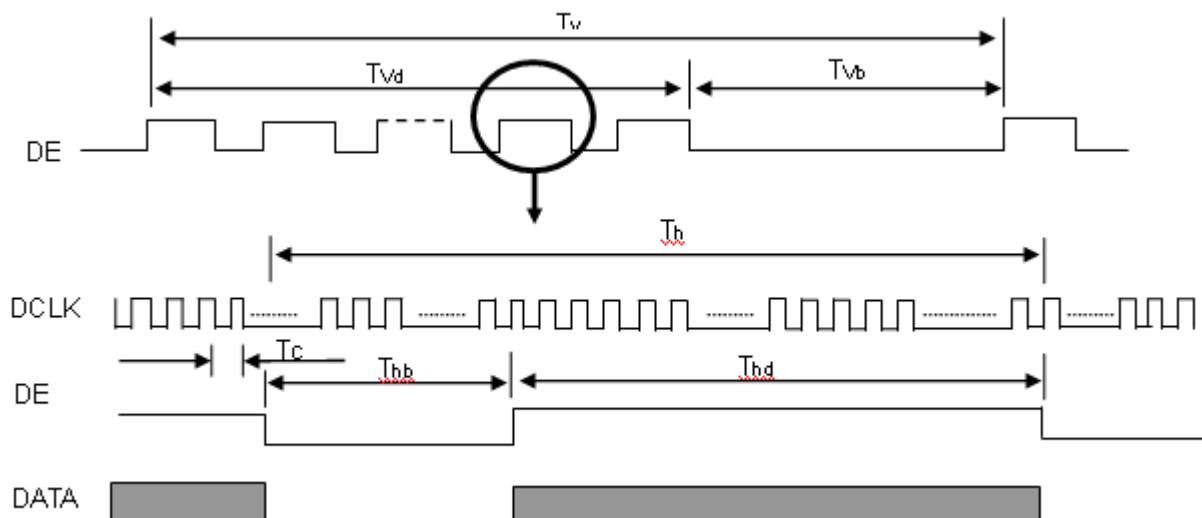
(2) Please make sure the range of pixel clock has follow below equation:

$$F_c(\max) \geq Fr \times Tv \times Th$$

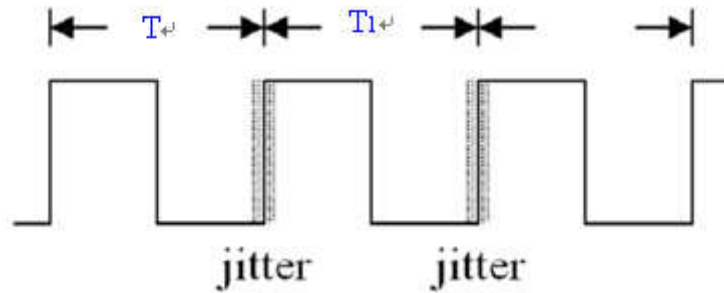
$$Fr \times Tv \times Th \geq F_c(\min)$$

(3) The Tv(Tvd+Tvb) must be integer, otherwise, this module would operate abnormally

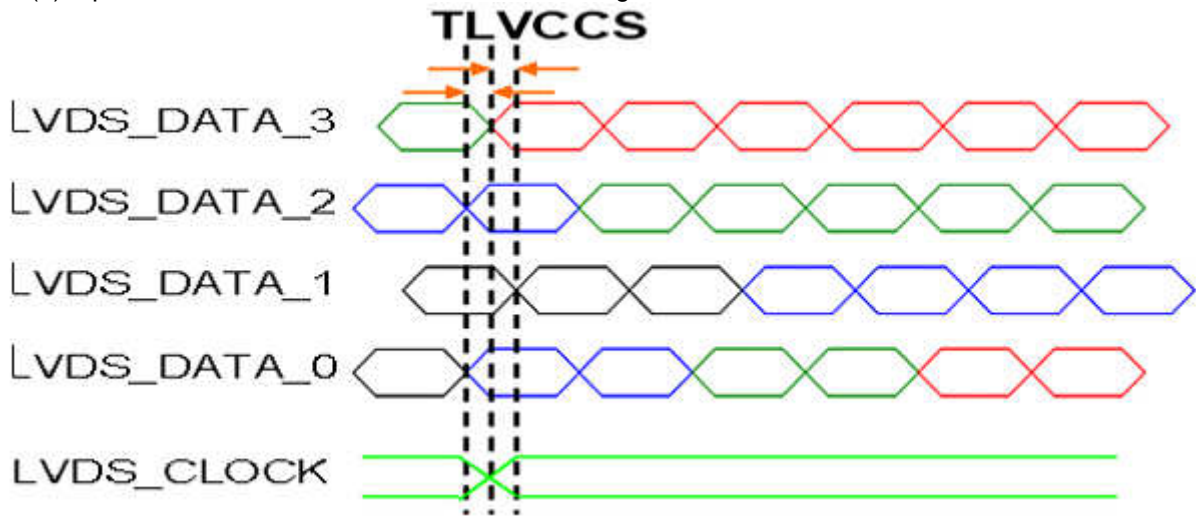
INPUT SIGNAL TIMING DIAGRAM



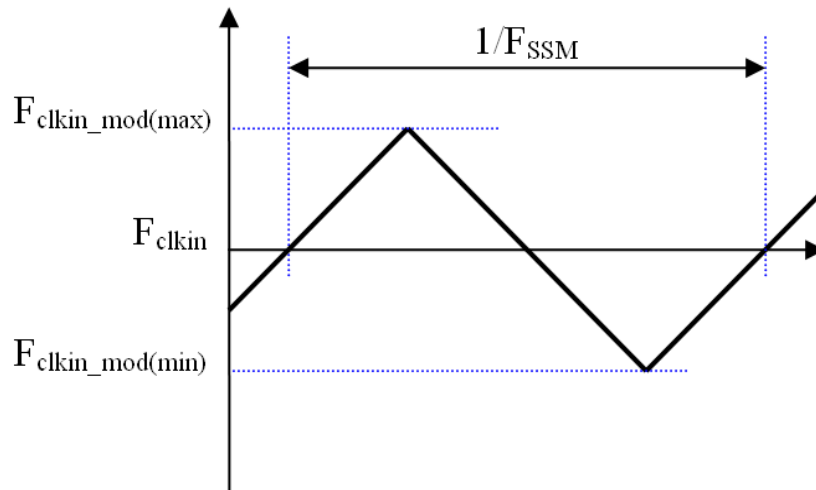
Note (4) The input clock cycle-to-cycle jitter is defined as below figures. $Trcl = |T_1 - T_1|$



Note (5) Input Clock to data skew is defined as below figures.

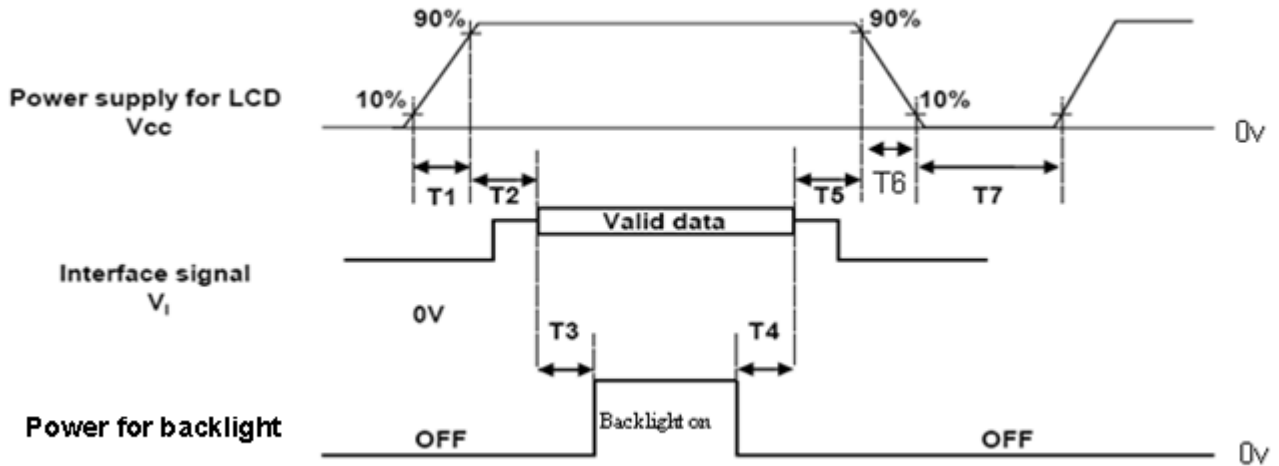


Note (6) The SSCG (Spread spectrum clock generator) is defined as below figures.



4.6 POWER ON/OFF SEQUENCE

The power sequence specifications are shown as the following table and diagram.



Timing Specifications:

Parameters	Values			Units
	Min	Typ.	Max	
T1	0.5	-	10	ms
T2	0	30	50	ms
T3	200	250	-	ms
T4	100	250	-	ms
T5	-	20	50	ms
T6	0.1	-	100	ms
T7	1000	-	-	ms

Note (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.

Note (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.

Note (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.

Note (4) T7 should be measured after the module has been fully discharged between power off and on period.

Note (5) Interface signal shall not be kept at high impedance when the power is on.

Note (6) CMI won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.

Note (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "t6 spec".

5. OPTICAL CHARACTERISTICS

5.1 TEST CONDITIONS

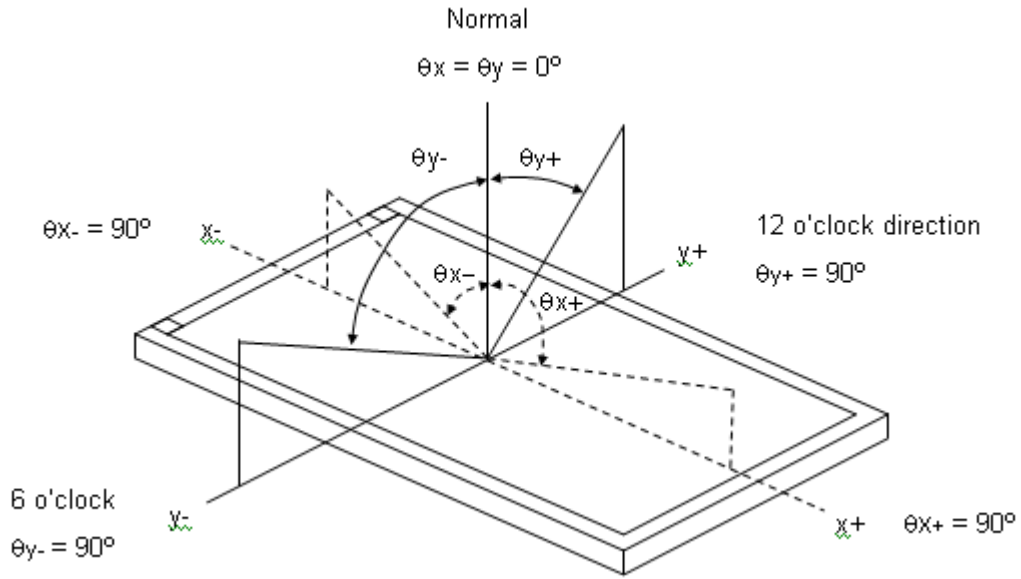
Item	Symbol	Value	Unit
Ambient Temperature	Ta	25±2	°C
Ambient Humidity	Ha	50±10	%RH
Supply Voltage	According to typical value in "ELECTRICAL CHARACTERISTICS"		
Input Signal			
LED Light Bar Input Current Per Input Pin			
Input Pin			

5.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown in 5.2. The following items should be measured under the test conditions described in 5.1 and stable environment shown in Note (5).

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note					
Color Chromaticity (CIE 1931)	Red	Rx	$\theta_x=0^\circ, \theta_y=0^\circ$ CS-2000 R=G=B=255 Gray scale	Typ - 0.03	0.635	Typ + 0.03	(1), (5)					
		Ry			0.340							
	Green	Gx			0.312							
		Gy			0.626							
	Blue	Bx			0.158							
		By			0.058							
	White	Wx			0.313							
		Wy			0.329							
	Center Luminance of White (Center of Screen)	L _c						200	250	-	cd/m ²	(4), (5)
	Contrast Ratio	CR						700	1000	-	-	(2), (5)
Response Time	T _R	$\theta_x=0^\circ, \theta_y=0^\circ$	-	1	4	ms	(3)					
	T _F		-	4	6							
White Variation	W	$\theta_x=0^\circ, \theta_y=0^\circ$	75	80		%	(5), (6)					
Viewing Angle	Horizontal	$\theta_{x-} + \theta_{x+}$	CR ≥ 10	150	170	-	Deg.	(1), (5)				
	Vertical	$\theta_{y-} + \theta_{y+}$		140	160	-						
Viewing Angle	Horizontal	$\theta_{x-} + \theta_{x+}$	CR ≥ 5	160	178	---	Deg.	(1), (5)				
	Vertical	$\theta_{y-} + \theta_{y+}$		150	170	---						

Note (1) Definition of Viewing Angle (θ_x, θ_y):



Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{255} / L_0$$

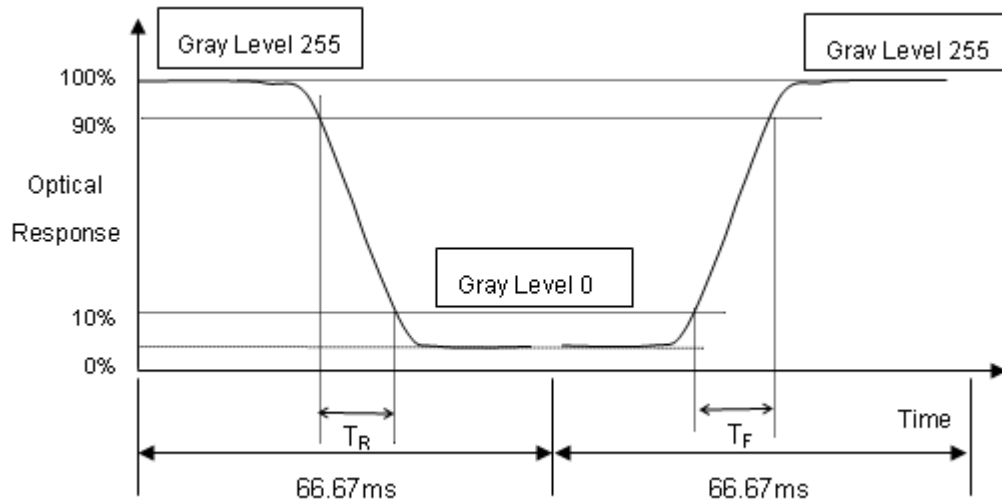
L255: Luminance of gray level 255

L 0: Luminance of gray level 0

$$\text{CR} = \text{CR} (5)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

Note (3) Definition of Response Time (T_R, T_F):



Note (4) Definition of Luminance of White (L_C):

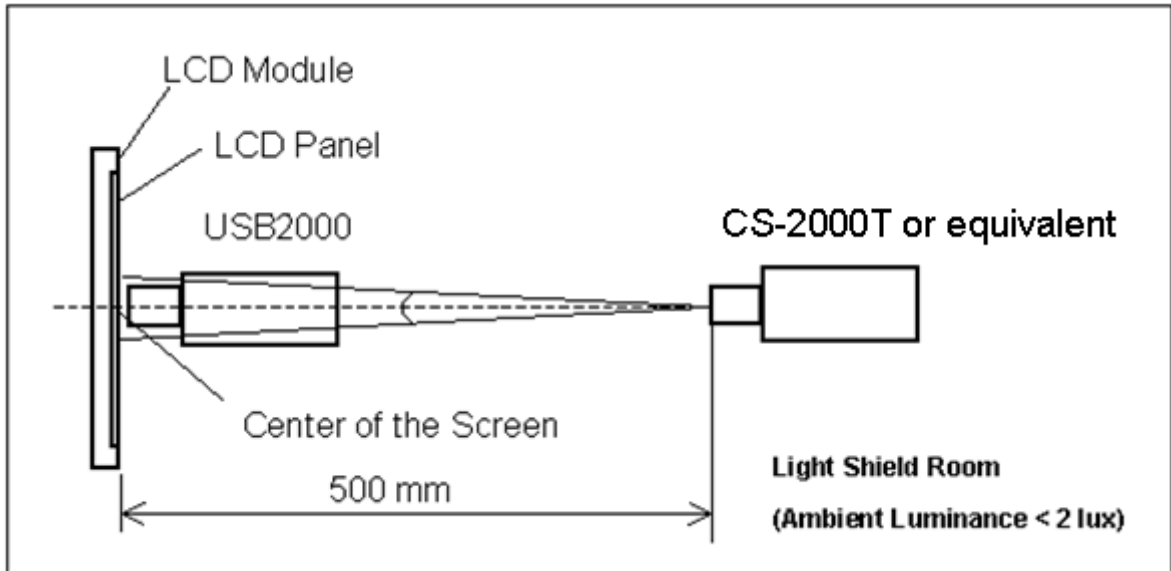
Measure the luminance of gray level 255 at center point

$$L_C = L(5)$$

$L(x)$ is corresponding to the luminance of the point X at Figure in Note (6).

Note (5) Measurement Setup:

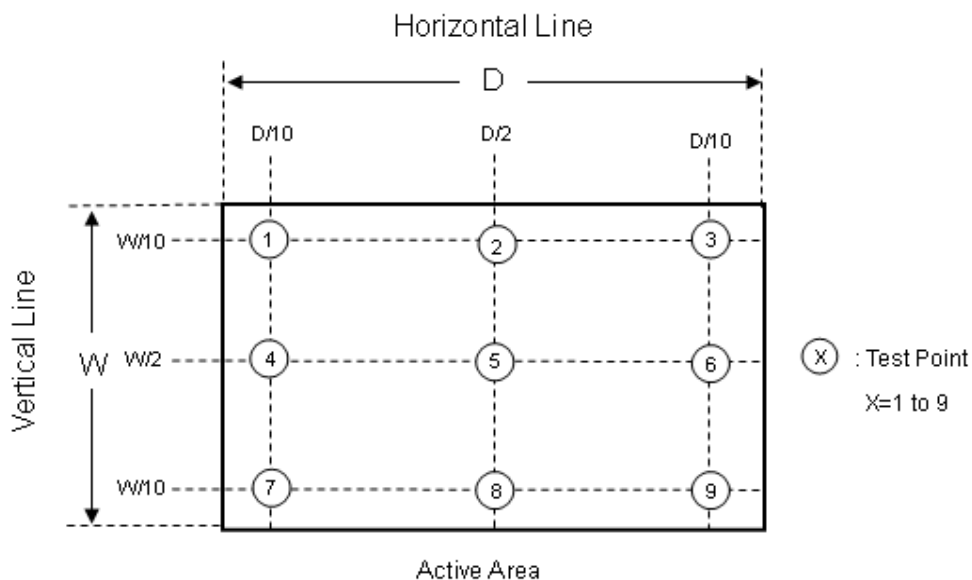
The LCD module should be stabilized at given temperature for 40 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room.



Note (6) Definition of White Variation (δW):

Measure the luminance of gray level 255 at 9 points

$$\delta W = (\text{Minimum } [L(1) \sim L(9)] / \text{Maximum } [L(1) \sim L(9)]) * 100\%$$



6. RELIABILITY TEST ITEM

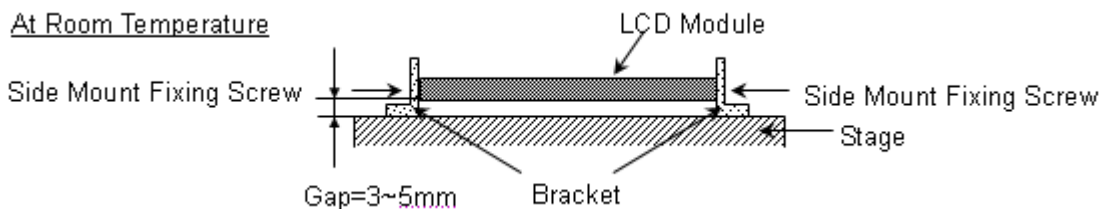
Items	Required Condition	Note
Temperature Humidity Bias (THB)	Ta= 50°C , 80%RH, 240hours	(1) (2)
High Temperature Operation (HTO)	Ta= 50°C , 240hours	(1) (2)
Low Temperature Operation (LTO)	Ta= 0°C , 240hours	(1) (2)
High Temperature Storage (HTS)	Ta= 60°C , 240hours	(1) (2)
Low Temperature Storage (LTS)	Ta= -20°C , 240hours	(1) (2)
Vibration Test (Non-operation)	Acceleration: 1.5 G Wave: Half-sine Frequency: 10 - 300 Hz Sweep: 30 Minutes each Axis (X, Y, Z)	(3)
Shock Test (Non-operation)	Acceleration: 50 G Wave: Half-sine Active Time: 11 ms Direction : ± X, ± Y, ± Z.(one time for each Axis)	(3)
Thermal Shock Test (TST)	-20°C/30min , 60°C / 30min , 100 cycles	(1) (2)
On/Off Test	25°C , On/10sec , Off /10sec , 30,000 cycles	(1) (2)
ESD (Electro Static Discharge)	Contact Discharge: ± 8KV, 150pF(330Ω)	(1)
	Air Discharge: ± 15KV, 150pF(330Ω)	(1)
Altitude Test	Operation:16,404 ft / 24hours Non-Operation:30,000 ft / 24hours	(1) (2)

Note (1) criteria : Normal display image with no obvious non-uniformity and no line defect.

Note (2) Evaluation should be tested after storage at room temperature for more than two hour

Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

The fixing condition is shown as below:



7. MECHANICAL STRENGTH CHARACTERISTICS

7.1 MECHANICAL STRENGTH SPECIFICATIONS

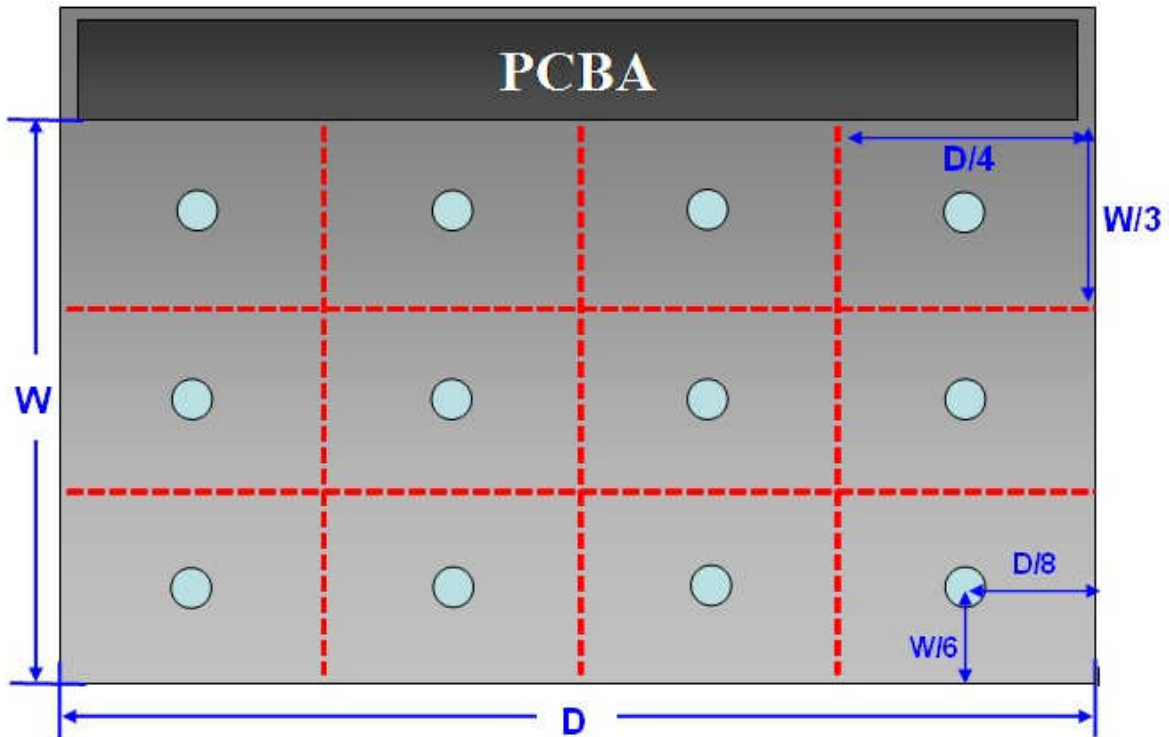
Item	Condition	Min	Unit	Note
Mechanical Strength	128 th Gray Pattern	0.6	Kgf	

7.2 TEST CONDITIONS

Items	Description
Test Condition	1. Ambient Illumination : 10~15 lux 2. Test Pattern : 128 Gray 3. Distance of the judgment : 30cm from the surface of module 4. Viewing angle of the judgment : Front
Gage Information	1. Push pull guage a. Model name : HF-50, maker : ALGOL b. Shape of gage tip - Diameter : 2mm - Thickness : 2mm
Definition of Minimum force	To measure minimum force when operator detects any white spot and light leakage that have occurred while operator presses on back side of module with push pull gage.

7.3 DEFINITION OF TEST POINTS

Measure the minimum force of test points at 128th Gray pattern. The test points at back side of module area is showing as below (except PCBA).



8. PACKING

8.1 PACKING SPECIFICATIONS

- (1) 11 LCD modules / 1 Box
- (2) Box dimensions: 440(L) X 280 (W) X 375(H) mm
- (3) Weight: approximately: 17.45kg (11 modules per box)

8.2 PACKING METHOD

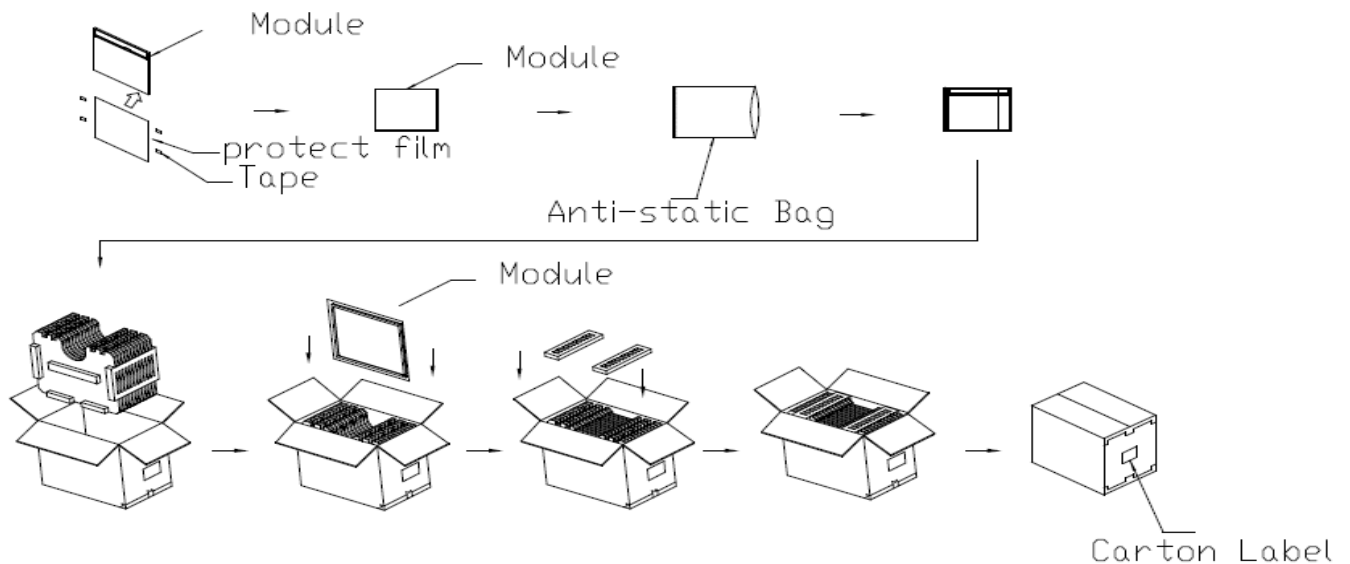
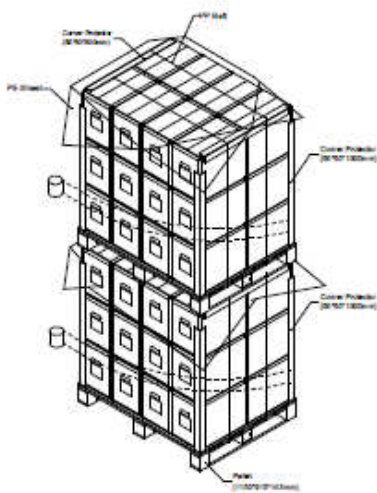


Figure. 7-1 Packing method

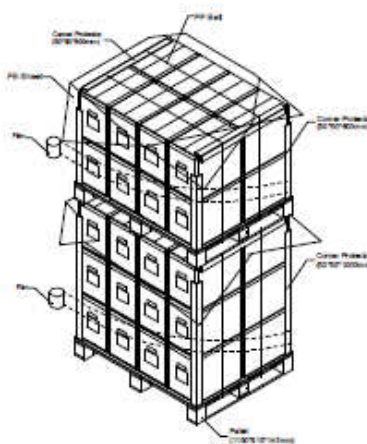
8.3 PALLET

棧板堆疊包膜型式

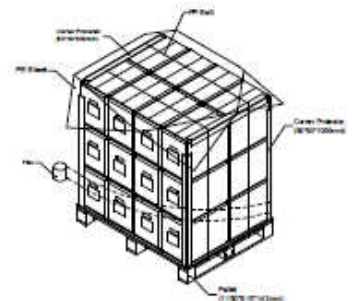
Sea / Land Transportation (40ft HQ Container)



Sea / Land Transportation (40ft Container)

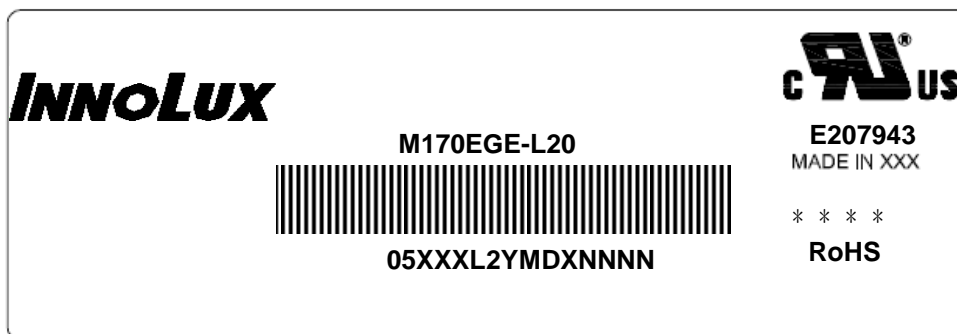


Air Transportation



9. INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.



(a) Model Name: M170EGE-L20

(b) Revision: Rev. XX, for example: A0, A1... B1, B2... or C1, C2...etc.

(c) CMI barcode definition:

Serial ID: XX-XX-X-XX-YMD-L-NNNN

Code	Meaning	Description
XX	INX internal use	-
XX	Revision	Cover all the change
X	INX internal use	-
XX	INX internal use	-
YMD	Year, month, day	Year: 2001=1, 2002=2, 2003=3, 2004=4... Month: 1~12=1, 2, 3, ~, 9, A, B, C Day: 1~31=1, 2, 3, ~, 9, A, B, C, ~, W, X, Y, exclude I, O, and U.
X	INX internal use	Grade Code
NNNN	Serial number	Manufacturing sequence of product

(d) Customer's barcode definition:

Serial ID: CM-H0E20-X-X-X-XX-L-XX-L-YMD-NNNN

Code	Meaning	Description
CM	Supplier code	INX =CM
H0E20	Model number	M170EGE-L20= H0E20
X	Revision code	Non ZBD: 1,2,~,8,9 / ZBD: A~Z
X	Source driver IC code	Century=1, CLL=2, Demos=3, Epson=4, Fujitsu=5, Himax=6, Hitachi=7, Hynix=8, LDI=9, Matsushita=A, NEC=B, Novatec=C, OKI=D, Philips=E, Renesas=F, Samsung=G, Sanyo=H, Sharp=I, TI=J, Topro=K, Toshiba=L, Windbond=M, ILITEK=Q, Fiti=Y, None IC =Z
X	Gate driver IC code	
XX	Cell location	Tainan Taiwan=TN, Ningbo China=CN, Hsinchu Taiwan=SC
L	Cell line #	1,2,~,9,A,B,~,Y,Z
XX	Module location	Tainan, Taiwan=TN ; Ningbo China=NP, Shenzhen China=SH
L	Module line #	1,2,~,9,A,B,~,Y,Z
YMD	Year, month, day	Year: 0~9, 2001=1, 2002=2, 2003=3...2010=0, 2011=1, 2012=2... Month: 1~12=1, 2, 3, ~, 9, A, B, C Day: 1~31=1, 2, 3, ~, 9, A, B, C, ~, T, U, V
NNNN	Serial number	By LCD supplier

(e) FAB ID(UL Factory ID):

Region	Factory ID
TWINX	GEMN
NBCMI	LEOO
NBCMI	VIRO
NBCME	CANO
NHCM1	CAPG

10. PRECAUTIONS

10.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1) Do not apply rough force such as bending or twisting to the module during assembly.
- (2) To assemble or install module into user's system can be only in clean working areas. The dust and oil may cause electrical short or worsen the polarizer.
- (3) It's not permitted to have pressure or impulse on the module because the LCD panel and Backlight will be damaged.
- (4) Always follow the correct power sequence when LCD module is connecting and operating. This can prevent damage to the CMOS LSI chips during latch-up.
- (5) Do not pull the I/F connector in or out while the module is operating.
- (6) Do not disassemble the module.
- (7) Use a soft dry cloth without chemicals for cleaning, because the surface of polarizer is very soft and easily scratched.
- (8) It is dangerous that moisture come into or contacted the LCD module, because moisture may damage LCD module when it is operating.
- (9) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (10) When ambient temperature is lower than 10°C may reduce the display quality. For example, the response time will become slowly.

10.2 STORAGE PRECAUTIONS

- (1) Do not leave the module in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0°C to 35°C and relative humidity of less than 70%
- (2) Do not store the TFT – LCD module in direct sunlight
- (3) The module should be stored in dark place. It is prohibited to apply sunlight or fluorescent light in storing

10.3 OPERATION PRECAUTIONS

- (1) The LCD product should be operated under normal condition.
Normal condition is defined as below :
Temperature : 20±15°C
Humidity: 65±20%
Display pattern : continually changing pattern(Not stationary)
- (2) If the product will be used in extreme conditions such as high temperature, high humidity, high altitude, display pattern or operation time etc... It is strongly recommended to contact CMI for application engineering advice. Otherwise, its reliability and function may not be guaranteed.

10.4 SAFETY PRECAUTIONS

- (1) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, skin or clothes, it has to be washed away thoroughly with soap.
- (2) After the module's end of life, it is not harmful in case of normal operation and storage.

10.5 SAFETY STANDARDS


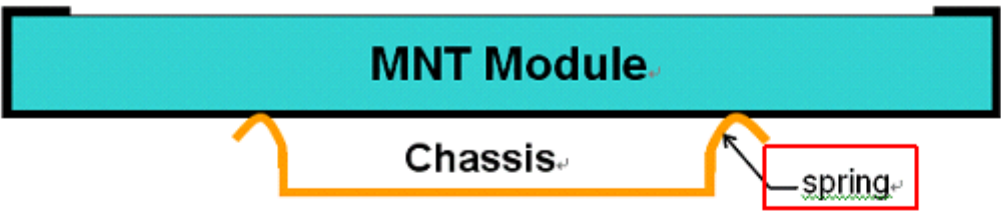

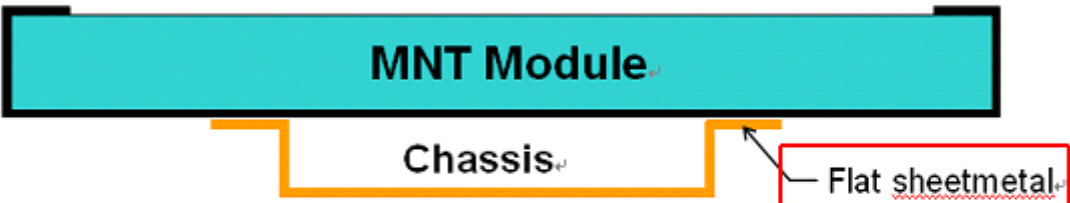
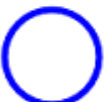

The LCD module should be certified with safety regulations as follows:

- (1) UL60950-1 or updated standard.
- (2) IEC60950-1 or updated standard.

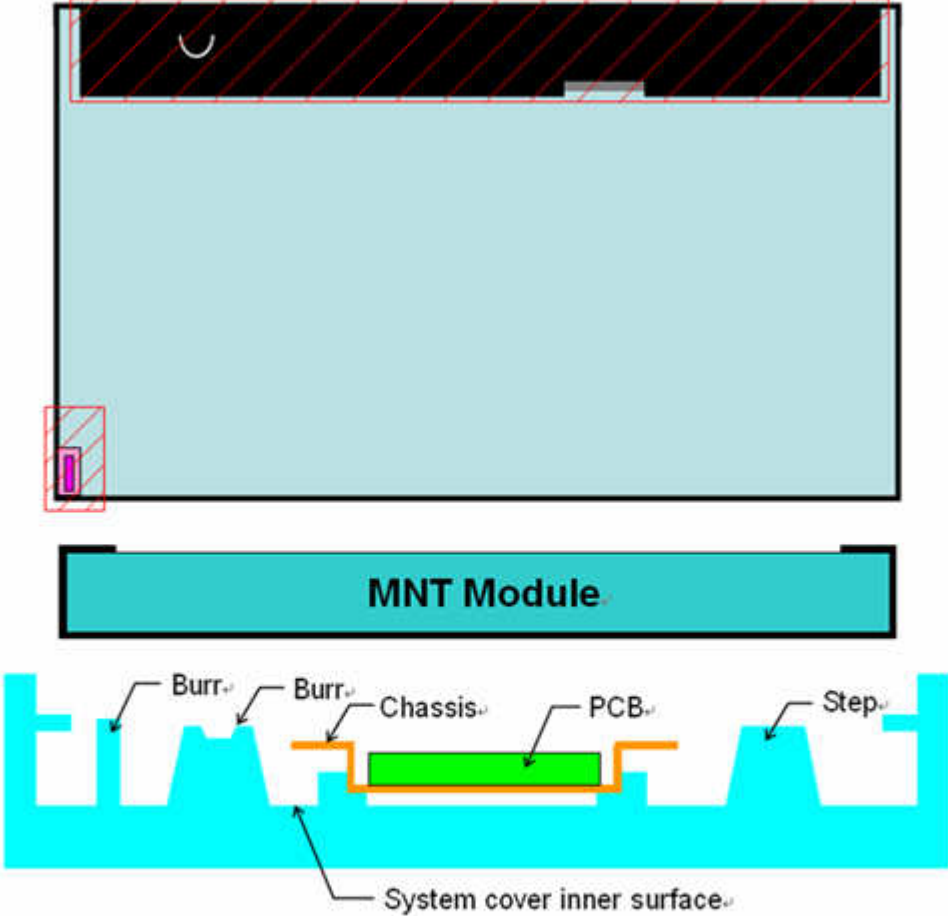

10.6 OTHER

When fixed patterns are displayed for a long time, remnant image is likely to occur.

APPENDIX 1. SYSTEM COVER DESIGN NOTICE

1.	Set Chassis and MNT Module touching Mode
	 <p>MNT Module</p> <p>Chassis</p> <p>spring</p>
	 <p>MNT Module</p> <p>Chassis</p> <p>Flat sheetmetal</p>
	 <p>MNT Module</p> <p>Chassis</p> <p>EMI Shielding Gasket (Tape/Sponge)</p>
<p>Definition</p>	<p>a) To prevent from abnormal display & white spot after Mechanical test, it is not recommended to used <u>spring</u> type chassis.</p> <p>b) We suggest the contact mode between Chassis and Module rear cover is <u>Tape/Sponge</u>, second is <u>Flat sheetmetal</u> type chassis (Don't interference from flat sheetmetal of chassis to rear cover of Module).</p>

2	Tape/sponge design on system inner surface
<p>The diagram illustrates the correct and incorrect placement of Tape/Sponge on the system inner surface. The top part shows a cross-section of the system with an MNT Module, Chassis, system front bezel, and System rear bezel. Red arrows point to the correct placement of Tape/Sponge between the chassis and the module rear cover. Below this, two diagrams illustrate incorrect placements: one with four separate pieces of Tape/Sponge (marked with a red X) and one with a single large piece of Tape/Sponge (marked with a blue circle).</p>	
Definition	<p>a) To prevent from abnormal display & white spot after Mechanical test, We suggest using Tape/Sponge as medium between chassis and Module rear cover could reduce the occurrence of white spot.</p> <p>b) When using the Tape/Sponge, suggest it be lay over between set chassis and module rear cover. it is not recommended to add tape/sponge in separate location. Since each tape/sponge may act as pressure concentration location.</p>

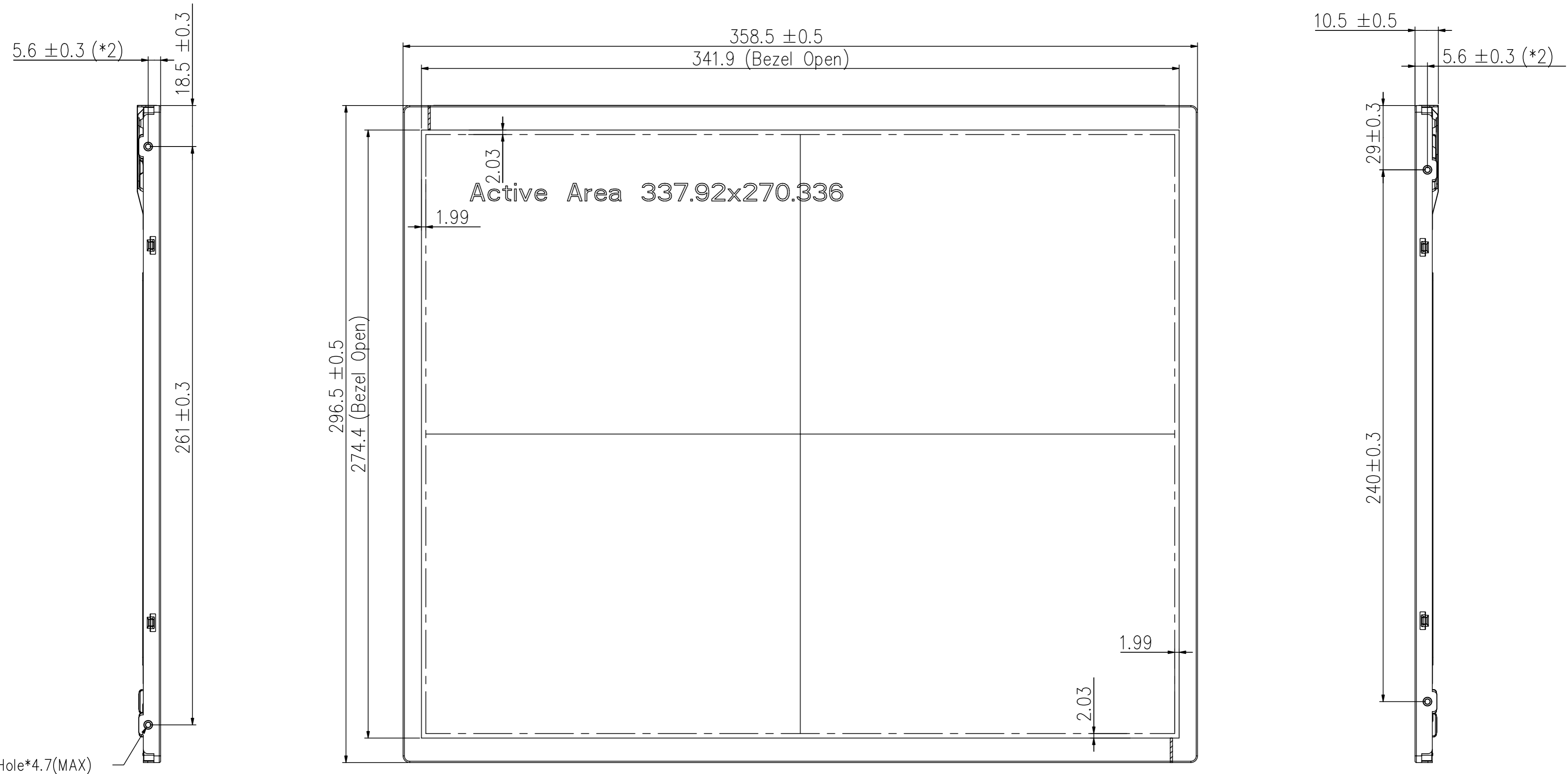
3	System inner surface examination
 <p>The diagram illustrates the system inner surface examination. It shows a cross-section of a system cover with a hatched area at the top. Below it is a light blue rectangular area representing the system cover inner surface. At the bottom, a cyan-colored structure represents the system cover inner surface with various features labeled: Burr, Burr, Chassis, PCB, and Step. A red hatched area is shown on the left side of the cyan structure, indicating a specific area of interest.</p>	
Definition	<p>a). Burr at logo edge, step, protrusion or PCB board will easily cause white spot.</p> <p>b). Keeping flat surface underneath module is recommended.</p> <p>c). The area () on Module PCBA and Light bar connector should keep at least 1mm gap to any structure with System cover inner surface.</p>

4	The overlapping part on System's Chassis and electric wire needs gap structure.
Definition	The overlapping part on System's Chassis and electric wire (FPC > FFC and wire) needs gap structure to avoid display of white spot by pressing overlapping part cause interference.

5	System cover's ventilation outlet structure
Definition	To prevent from abnormal display of light leakage, We suggest to set ventilation outlet structure on side of Module Light bar in system cover inner surface.

APPENDIX 2. OUTLINE DRAWING

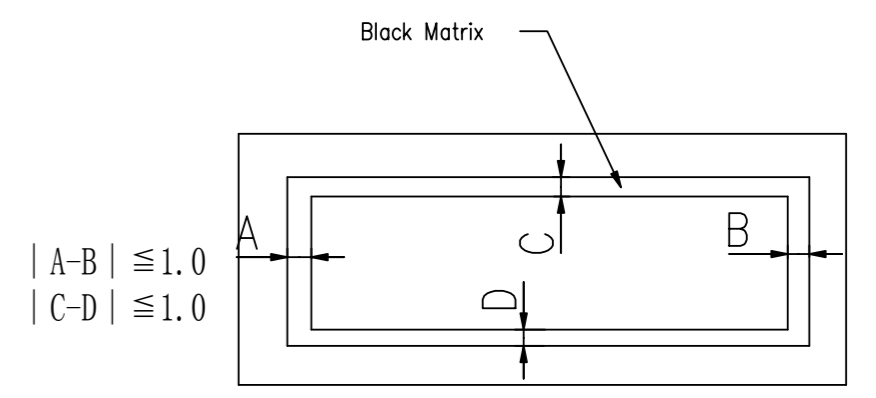
REV	EC NUMBER	DESCRIPTION	DATE
△		First Release	2017/03/02



M3 Hole*4.7(MAX)

SCALE 1

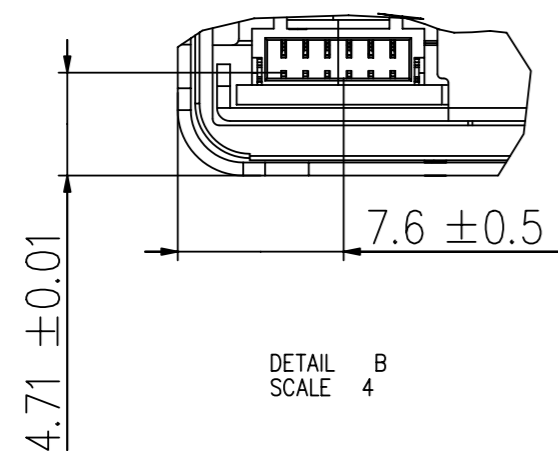
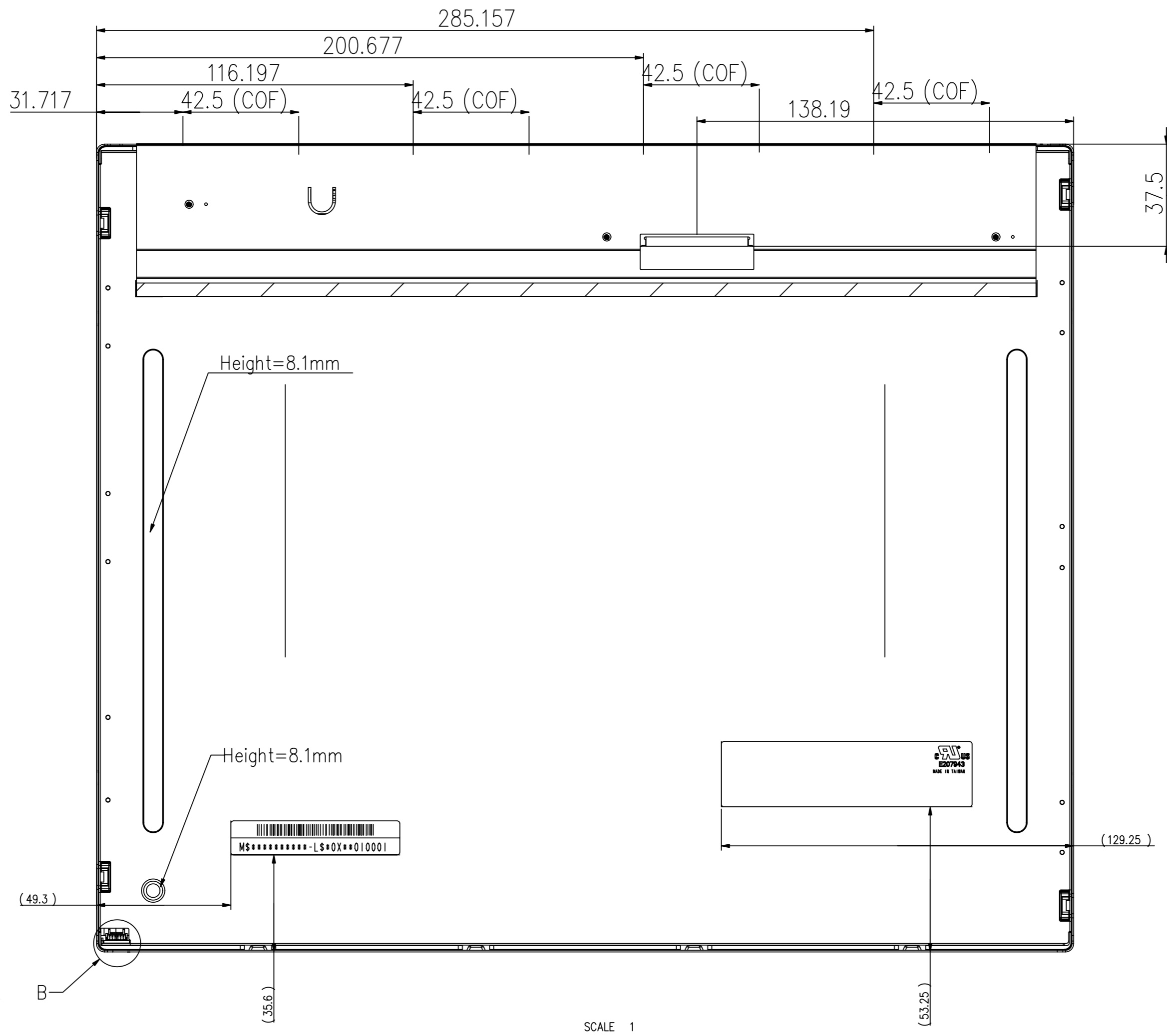
- NOTE:
1. TORQUE OF M3 USER HOLE SHOULD BE WITHIN 5 kgf-cm, AND JUST RESCREW 10 TIMES
 2. TOLERANCE WITHOUT NOTICED TO BE ± 0.5 mm.
 3. I/F Connector Spec: FOXCONN GS23301-0321R-7H/P-TWO 187098-30091/FCN WF13-422-3033
 4. THE COF AND FPC AREA IS WEAK & SENSITIVE, PLEASE DON'T PRESS THE COF AND FPC AREA.



① USER DIMENSION	② CONTROL DIMENSION	DATE	SCALE	UNIT	④
APPROVED	JC. Young	2017/03/02	1	mm	REV A
CHECKED	Haojun.Yu				DWG NO. DN0668243
DESIGNED	Vicky.Wang				PART DESCRIPTION module_M170EGE-L20
					FIG. NO. 1/2
					REV. NO. A1



REV	EC NUMBER	DESCRIPTION	DATE
△		First Release	2017/05/02



SEE DETAIL B

SCALE 1

- NOTE:
1. TORQUE OF M3 USER HOLE SHOULD BE WITHIN 5 kgf-cm, AND JUST RESCREW 10 TIMES
 2. TOLERANCE WITHOUT NOTICED TO BE ± 0.5 mm.
 3. I/F Connector Spec: FOXCONN GS23301-0321R-7H/P-TWO 187098-30091/FCN WF13-422-3033
 4. THE COF AND FPC AREA IS WEAK & SENSITIVE, PLEASE DON'T PRESS THE COF AND FPC AREA.

APPROVED	JC. Young	DATE	2017/05/02	SCALE	1	UNIT	mm
CHECKED	Hao Jun Yu	PART NUMBER	DN0668243	REV	A		
DESIGNED	Vicky Wang	PART DESCRIPTION	module_M170EGE-L20	SHEET NUMBER	2/2		
		REV	A1				

